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## Product Change Notification - JAON-04DHCS000

**Date:** 13 Jun 2016  
**Product Category:** SMSC  
**Notification subject:** CCB 2512 Final Notice: Qualification of CuPdAu bond wire in selected products of the 0.18 and 0.16um GF wafer technologies available in 36L VQFN package at ANAC assembly site.  
**Notification text:** **PCN Status:**  
 Final notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18 and 0.16um GF wafer technologies available in 36L VQFN package at ANAC assembly site.

**Pre Change:**

Palladium coated copper wire (PdCu) bond wire

**Post Change:**

Palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	ANAC assembly site	ANAC assembly site
<b>Wire material</b>	PdCu wire	CuPdAu wire
<b>Die attach material</b>	8290	8290
<b>Molding compound material</b>	G700	G700
<b>Lead frame material</b>	C194	C194

**Impacts to Data Sheet:**  
None

**Reason for Change:**  
To improve productivity and qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

**Change Implementation Status:**  
In Progress

**Estimated First Ship Date:**  
June 30, 2016 (date code: 1626)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Summary Table:**

	March 2016					----->	June 2016				
	09	10	11	12	13		22	23	24	25	26
WW											
Initial PCN Issue Date		X									
Qual Report Availability								X			
Final PCN Issue Date								X			
Estimated Implementation Date											X

**Markings to Distinguish Revised from Unrevised Devices:**  
Traceability code

**Revision History:**  
**March 10, 2016:** Issued initial notification.  
**June 13, 2016:** Issued final notification. Attached the qualification report. Updated the affected parts list.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):** [PCN\\_JAON-04DHCS000\\_Qual\\_Report.pdf](#)  
[PCN\\_JAON-04DHCS000\\_Affected\\_CPN.pdf](#)  
[PCN\\_JAON-04DHCS000\\_Affected\\_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_ JAON-04DHCS000
CATALOG_PART_NBR
USB2240-AEZG-05
USB2240-AEZG-06
USB2240-AEZG-06-TR
USB2240I-AEZG-06
USB2241-AEZG-06
USB2241I-AEZG-06
USB2244-AEZG-06
USB2244-AEZG-06-CA1
USB2244-AEZG-06-TR
USB2244I-AEZG-06
USB2244I-AEZG-06-TR
USB2514-AEZG-TR
USB2514I-AEZG-TR
USX2061-AEZG